



Final Product/Process Change Notification

Document #:FPCN25678X

Issue Date:29 Jan 2024

Title of Change:	Wafer Fab Site Addition of onsemi, CZ4 Roznov as alternate fab site for HDG4 (High Side Double Diffused MOS) Technology	
Proposed First Ship date:	03 May 2024 or earlier if approved by customer	
Contact Information:	Contact your local onsemi Sales Office or Terry.Chan@onsemi.com	
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.	
Additional Reliability Data:	Contact your local onsemi Sales Office or Jacob.Saliba@onsemi.com	
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com	
Marking of Parts/ Traceability of Change:	Material will be traceable with onsemi lot trace code & date code.	
Change Category:	Wafer Fab Change	
Change Sub-Category(s):	Manufacturing Site Addition	
Sites Affected:		
onsemi Sites	External Foundry/Subcon Sites	
onsemi Roznov, Czech Republic	None	
Description and Purpose:		
onsemi wants to notify its customers regarding the qualification of HDG4 technology at onsemi CZ4 Roznov, Czech Republic wafer fab, to enable expanded capacity for this technology.		
Upon the expiration of this notification, all products listed here will be dual sourced from either Diode, Maine, USA or onsemi CZ4, Roznov wafer fab.		
	Before	After
Fab Site (HDG4 technology)	Maine/DIODE (USA)	Maine/DIODE (USA) / onsemi CZ4 (Roznov)
Probe Location	BK6 (Bucheon, Korea) / GTK (Greatek, Taiwan)	GTK (Greatek Taiwan)
Back grind Location	Maine/DIODE (USA)	Maine/DIODE (USA) / onsemi CZ4 (Roznov)
There are no product material changes as a result of this change.		
There is no product marking change as a result of this change.		



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Reliability Data Summary:

QV DEVICE NAME: FAN7380MX

RMS: O87670

PACKAGE: SOIC8N

Test	Specification	Condition	Interval	Results
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260°C, Pre TC, uHAST, HAST for surface mount pkgs only		0/693
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, biased	96 hours	0/231
High Temperature Operating Life	JESD22-A108	Ta=125°C, 100% max rated Vcc	1008 hours	0/231
High Temperature Storage Life	JESD22-A103	Ta= 150°C	1008 hours	0/231
Temperature Cycling	JESD22-A104	Ta= -65°C to +150°C	500 cycles	0/231
Unbiased Highly Accelerated Stress Test	JESD22-A118	Ta=130°C, 85% RH, 18.8psig, unbiased	96 hours	0/231

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle
FAN7383MX	FAN7380MX
FAN73833MX	FAN7380MX
FAN7380MX	FAN7380MX

Appendix A: Changed Products

PCN#: FPCN25678X
Issue Date: Jan 28, 2024

DIKG: DIGI-KEY

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
FAN7383MX		FAN7380MX	#NONE	
FAN7380MX		FAN7380MX	#NONE	
FAN73833MX		FAN7380MX	#NONE	